HS code (HS2012)	Description	Base Rate	Staging Category
8483.30	-Bearing housings, not incorporating ball or roller bearings; plain shaft bearings:		
8483.30.10	---Of a kind used as components in passenger motor vehicles	5.0%	D
8483.30.90	---Other	5.0%	B
8483.40	-Gears and gearing, other than toothed wheels, chain sprockets and other transmission elements presented separately; ball or roller screws; gear boxes and other speed changers, including torque converters:		
8483.40.1	---Of a kind used for internal combustion piston engines of the vehicles of 8701.20.00, 8702, 8703, 8704 or 8705, other than for fuel injection equipment for compression-ignition engines (diesel or semi-diesel engines):		
8483.40.11	----Of a kind used as components in passenger motor vehicles	5.0%	C
8483.40.19	----Other	5.0%	B
8483.40.90	---Other	5.0%	C
8483.50	-Flywheels and pulleys, including pulley blocks:		
8483.50.1	---Of a kind used for internal combustion piston engines of the vehicles of 8701.20.00, 8702, 8703, 8704 or 8705, other than for fuel injection equipment for compression-ignition engines (diesel or semi-diesel engines):		
8483.50.11	----Of a kind used as components in passenger motor vehicles	5.0%	D
8483.50.19	----Other	5.0%	B
8483.50.90	---Other	5.0%	D
8483.60	-Clutches and shaft couplings (including universal joints):		
8483.60.10	---Of a kind used as components in passenger motor vehicles	5.0%	D
8483.60.90	---Other	5.0%	B
8483.90.00	-Toothed wheels, chain sprockets and other transmission elements presented separately; parts	5.0%	D
8484	GASKETS AND SIMILAR JOINTS OF METAL SHEETING COMBINED WITH OTHER MATERIAL OR OF TWO OR MORE LAYERS OF METAL; SETS OR ASSORTMENTS OF GASKETS AND SIMILAR JOINTS, DISSIMILAR IN COMPOSITION, PUT UP IN POUCHES, ENVELOPES OR SIMILAR PACKINGS; MECHANICAL SEALS:		
8484.10	-Gaskets and similar joints of metal sheeting combined with other material or of two or more layers of metal:		
8484.10.10	---Of a kind used as components in passenger motor vehicles	5.0%	C
8484.10.90	---Other	5.0%	B
8484.20.00	-Mechanical seals	5.0%	B
8484.90	-Other:		
8484.90.10	---Of a kind used as components in passenger motor vehicles	5.0%	D
8484.90.90	---Other	5.0%	B

HS code (HS2012)	Description	Base Rate	Staging Category
8486	MACHINES AND APPARATUS OF A KIND USED SOLELY OR PRINCIPALLY FOR THE MANUFACTURE OF SEMICONDUCTOR BOULES OR WAFERS, SEMICONDUCTOR DEVICES, ELECTRONIC INTEGRATED CIRCUITS OR FLAT PANEL DISPLAYS; MACHINES AND APPARATUS SPECIFIED IN NOTE 9(C) TO THIS CHAPTER; PARTS AND ACCESSORIES:		
8486.10	-Machines and apparatus for the manufacture of boules or wafers:		
8486.10.10	---Machines and apparatus, as follows: (a) for growing or pulling monocrystal semiconductor boules; (b) machine-tools for working material by removal of material, by the processes specified in 8456 (including laser or other light or photon beam, ionic-beam or electron beam processes); (c) spin dryers for semiconductor wafer processing; (d) sawing machines for sawing monocrystal semiconductor boules into slices; (e) grinding, polishing or lapping machines; (f) industrial or laboratory electric furnaces or ovens	0.0%	A
8486.10.20	---Machines and apparatus, NSA, which, but for the operation of Note 9(D) to this chapter, would be classified in 8543.70.00	0.0%	A
8486.10.30	---Machines and apparatus, NSA, for the treatment of materials by a process involving a change of temperature	5.0%	B
8486.10.90	---Other	5.0%	B
8486.20	-Machines and apparatus for the manufacture of semiconductor devices or of electronic integrated circuits:		
8486.20.10	---Machines and apparatus, as follows: (a) appliances (including spraying appliances) for wet-etching, developing, stripping or cleaning semiconductor wafers; (b) physical deposition apparatus (including apparatus for deposition by sputtering) on semiconductor wafers; (c) chemical vapour deposition apparatus; (d) machine-tools for working material by removal of material, by the processes specified in 8456 (including laser or other light or photon beam, ionic-beam or electron beam processes); (e) epitaxial deposition machines; (f) industrial or laboratory electric furnaces or ovens; (g) spinners for coating photographic emulsions on semiconductor wafers; (h) for dry-etching patterns on semiconductor materials; (ij) ion implanters for doping semiconductor materials; (k) apparatus for the projection or drawing of circuit patterns on sensitised semiconductor materials; (l) sawing machines for sawing wafers into chips; (m) dicing machines for scribing or scoring semiconductor wafers	0.0%	A